

HDAF SERIES

(2.00 mm) .0787"

RUGGED ELEVATED HIGH-DENSITY ARRAY

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HDAF

Insulator Material:

Black LCP

Contact Material:

Copper Alloy

Plating:

Au or Sn over

50 μ" (1.27 μm) Ni

Current Rating:

3.4 A per pin

(6 adjacent pins powered)

Operating Temp Range:

-55 °C to +125 °C

Working Voltage:

200 VAC

Mated Cycles:

100

RoHS Compliant:

Yes

Lead-Free Solderable:

Yes

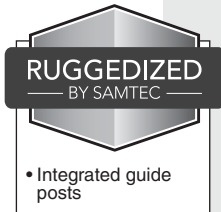
Mates with:
HDAM

Intermateable with
Molex HD Mezz

Open-pin-field for
Single-Ended
or Differential Pair
configurations

299,
195
and
143
pins

Lead-Free
Solder
Charge



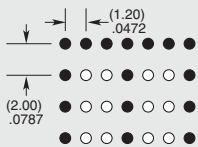
Elevated
stack
heights
of 20 mm,
25 mm,
30 mm
and 35 mm

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



DIFFERENTIAL APPLICATIONS



ARRAY	PAIR COUNT*
11x13	44
15x13	60
23x13	92

*2:1 S:G Ratio

ALSO AVAILABLE (MOQ Required)

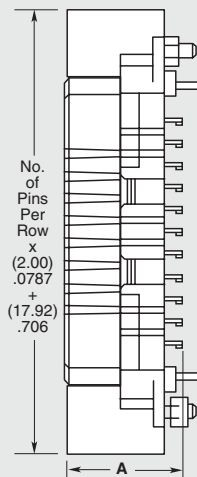
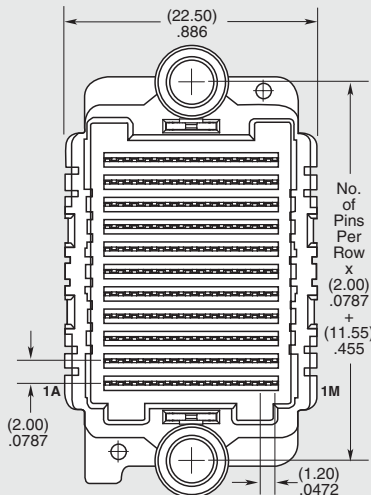
- Tin-Lead Solder Charge
- Other platings

Notes:

HD Mezz is a trademark of Molex Incorporated

Note: Some lengths, styles and options are non-standard, non-returnable.

HDAF	NO. OF PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	OTHER OPTION
	-11, -15, -23	Specify LEAD STYLE from chart	-S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on tails and guide pins	-13	-2 = Lead-Free Tin Alloy 95.5% Sn/ 3.8% Ag/ 0.7% Cu Solder Charge	-P = Pick & Place Pad



LEAD STYLE	A
-08.0	(10.51) .414
-18.0	(20.51) .807

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.